

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Hiroyuki WATANABE, et al.

Serial Number: 09/320,271

Filed: May 27, 1999

For: SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF



Group Art Unit: 2811

Attention: Appln Processing Division,  
Customer Correction Branch

#5  
8-3-99  
Payton

REQUEST FOR CORRECTED FILING RECEIPT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Date: July 9, 1999

Sir:

Please supply the undersigned attorney with a corrected filing receipt for the above-identified application. The undersigned also respectfully requests that the Patent and Trademark Office records be amended to reflect the correction.

In reviewing the official Filing Receipt, we noted an error in that the first priority document number is incorrect ("10-149465" should read - -10-149456- -). A copy of the Declaration is enclosed which indicates the correct number.

We are enclosing a copy of the filing receipt with the corrections highlighted.

In the event that any fees are required in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,

ARMSTRONG, WESTERMAN, HATTORI,  
MCLELAND & NAUGHTON

  
Stephen G. Adrian

Attorney for Applicants  
Reg. No. 32,878

RECEIVED  
JUL 13 1999  
TC 2800 MAIL ROOM

Atty. Docket No. 990559  
1725 K Street, N.W., Suite 1000  
Washington, DC 20006  
Tel: (202) 659-2930  
Fax: (202) 887-0357  
SGA/cs  
Enclosures: Copies of Filing Receipt and Declaration

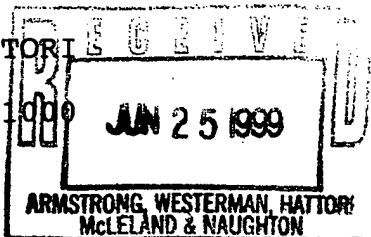
FILING RECEIPT



UNITED STATES DEPARTMENT OF COMMERCE  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTORNEY DOCKET NO.	DRWGS	TOT CL	IND CL
09/320,271	05/27/99	2811	\$760.00	990559	17	20	2

ARMSTRONG WESTERMAN HATTORI  
MCLELAND & NAUGHTON  
1725 K STREET NW SUITE 1000  
WASHINGTON DC 20006



Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Application Processing Division's Customer Correction Branch within 10 days of receipt. Please provide a copy of the Filing Receipt with the changes noted thereon.

Applicant(s)

HIROYUKI WATANABE, BISAI-SHI, JAPAN; HIDEKI MIZUHARA,  
BISAI-SHI, JAPAN; SHINICHI TANIMOTO, BISAI-SHI, JAPAN;  
ATSUHIRO NISHIDA, OGAKI-SHI, JAPAN; YOSHIKAZU YAMAOKA,  
OGAKI-SHI, JAPAN; YASUNORI INOUE, OGAKI-SHI, JAPAN.

FOREIGN APPLICATIONS-

JAPAN  
JAPAN

10-1494<sup>56</sup>5(P)  
10-308754(P)

05/29/98  
10/29/98

IF REQUIRED, FOREIGN FILING LICENSE GRANTED 06/23/99

TITLE

SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF

PRELIMINARY CLASS: 257

RECEIVED  
JUL 13 1999  
TC 2800 MAIL ROOM

DATA ENTRY BY: THOMAS, SHEILA

TEAM: 06 DATE: 06/23/99

|||||

A. W. H. McL &amp; N Docket No. \_\_\_\_\_

ARMSTRONG, WESTERMAN, HATTORI, MCLELAND &amp; NAUGHTON

**Declaration For U.S. Patent Application**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled  
(Insert Title) Semiconductor Device and Fabrication Method Thereof

the specification of which is attached hereto unless the following is checked:

☐ was filed on \_\_\_\_\_ as United States Application Number or PCT International Application Number \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) - (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

(List prior foreign applications. See note A on back of this page)	10-149456(P) (Number)	Japan (Country)	29/May/1998 (Day/Month/Year Filed)	Priority Claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
	10-308754(P) (Number)	Japan (Country)	29/October/1998 (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
	_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
	_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

(See note B on back of this page)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

_____ (Application Number)	_____ (Filing Date)
_____ (Application Number)	_____ (Filing Date)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of the application:

(List Prior U.S. Applications)	(Application Serial Number)	(Filing Date)	(Status) (patented, pending, abandoned)
	_____ (Application Serial Number)	_____ (Filing Date)	_____ (Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

James E. Armstrong, III, Reg. No. 18,366; William F. Westerman, Reg. No. 29,988; Ken-Ichi Hattori, Reg. No. 32,861; Le-Nhung McLeland, Reg. No. 31,541; Ronald F. Naughton, Reg. No. 24,616; John R. Pegan, Reg. No. 18,069; William G. Kratz, Jr., R. g. No. 22,631; Albert Tockman, Reg. No. 19,722; Mel R. Quintos, Reg. No. 31,898; Donald W. Hanson, Reg. No. 27,133; Stephen G. Adrian, Reg. No. 32,878; William L. Brooks, Reg. No. 34,129; John F. Carney, Reg. No. 20,276; Edward F. Welsh, Reg. No. 22,455; Patrick D. Muir, Reg. No. 37,403; Gay A. Spahn, Reg. No. 34,978; and John P. Kong, Reg. No. 40,054.

Please direct all communications to the following address:

ARMSTRONG, WESTERLATTORI,  
McLELAND & NAUGHTON  
1725 K Street, N.W., Suite 1000  
Washington, D.C. 20006  
Telephone: (202) 659-2930 Fax: (202) 887-0357

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name) Hiroyuki WATANABE(See note  
C above)Inventor's Signature Hiroyuki Watanabe Date May 20, 1999Residence Bisai-shi, Aichi, Japan Citizenship JapanesePost Office Address 13, Higashitatsuike, Kamisobue, Bisai-shi, Aichi, JapanFull name of second inventor (given name, family name) Hideki MIZUHARAInventor's Signature Hideki Mizuhara Date May 20, 1999Residence Bisai-shi, Aichi, Japan Citizenship JapanesePost Office Address 34-1, Yuukuno, Higashiitsushiro, Bisai-shi, Aichi, JapanFull name of third inventor (given name, family name) Shinichi TANIMOTOInventor's Signature Shinichi Tanimoto Date May 20, 1999Residence Bisai-shi, Aichi, Japan Citizenship JapanesePost Office Address 15-1, Yama, Sanjo, Bisai-shi, Aichi, JapanFull name of fourth inventor (given name, family name) Atsuhiko NISHIDAInventor's Signature Atsuhiko Nishida Date May 20, 1999Residence Ogaki-shi, Gifu, Japan Citizenship JapanesePost Office Address 239-3, Kido-cho, Ogaki-shi, Gifu, JapanFull name of fifth inventor (given name, family name) Yoshikazu YAMAOKAInventor's Signature Yoshikazu Yamaoka Date May 20, 1999Residence Ogaki-shi, Gifu, Japan Citizenship JapanesePost Office Address 1-815, Wagohonmachi, Ogaki-shi, Gifu, JapanFull name of sixth inventor (given name, family name) Yasunori INOUEInventor's Signature Yasunori Inoue Date May 20, 1999Residence Ogaki-shi, Gifu, Japan Citizenship JapanesePost Office Address 2-10, Kumano-cho, Ogaki-shi, Gifu, Japan

Full name of seventh inventor (given name, family name) \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Residence \_\_\_\_\_ Citizenship \_\_\_\_\_

Post Office Address \_\_\_\_\_

Full name of eighth inventor (given name, family name) \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Residence \_\_\_\_\_ Citizenship \_\_\_\_\_

Post Office Address \_\_\_\_\_